



Technical Data Sheet

DOWSIL™ 340 Heat Sink Compound

FEATURES & BENEFITS

- Non-flowing
- Moderate thermal conductivity
- No need for ovens or curing
- Heat flow away from circuitry components can increase reliability
- Compliant with MIL-DTL-47113

COMPOSITION

- Zinc Oxide
- Polydimethylsiloxane

White, non-curing and non-flowing thermally conductive compound

APPLICATIONS

- DOWSIL™ 340 Heat Sink Compound is suitable for thermal coupling of electrical devices and PCB assemblies to heat sinks.

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
One or Two-Part		One
Color		White
Viscosity	cP	542,000
	Pa-sec	542
Specific Gravity (Uncured)		2.1
Bleed	%	0.23
Thermal Conductivity	btu/hr-ft-°F	0.39
	W/m-K	0.67
Thermal Resistance at 40 psi	°C*cm ² /W	0.16
Penetration (worked)	1/10 mm	290
Evaporation	%	0.38
Shelf Life at 38°C	months	60

DESCRIPTION

Dow thermally conductive compounds are grease like silicone materials, heavily filled with heat-conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive heat sink seal to improve heat transfer from the electrical device or PCB system assemblies to the heat sink or chassis, thereby increasing the overall efficiency of the device. or PCB system assemblies are continually designed to deliver higher performance.

Especially in the area of consumer devices, there is also a continual trend towards smaller, more compact designs. In combination these factors typically mean that more heat is generated in the device. Thermal management of PCB system assemblies is a primary concern of design engineers. A cooler device allows for more efficient operation and better reliability over the life of the device. As such, thermally conductive compounds play an integral role here. Thermally conductive materials act as a thermal “bridge” to remove heat from a heat source (device) to the ambient via a heat transfer media (i.e. heat sink).

These materials have properties such as low thermal resistance, high thermal conductivity, and can achieve thin Bond Line Thicknesses (BLTs) which can help to improve the transfer of heat away from the device.

APPLICATION METHODS

- Automated or manual dispensing

SOLVENT EXPOSURE

In general, the product is resistance to minimal or intermittent solvent exposure, however best practice is to avoid solvent exposure altogether.

HANDLING

PRECAUTIONS

PRODUCT SAFETY

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USABLE LIFE AND STORAGE

The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated Exp. Date found on the label.

LIMITATIONS

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

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